





0,50mm HI-SPEED HEADER QTH SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QTH

Insulator Material: Liquid Crystal C 7 Polymer

Terminal Material: Phosphor Bronze Plating:

Au over 50μ" (1,27μm) Ni Current Rating: Contact: 1.0A @ 30°C Temperature Rise Ground Plane: 7.8A @ 30°C Temperature Rise

Operating Temp Range: -55°C to +125°C Voltage Rating: 125 VAC (5mm Stack Height) Max Cycles:

Unmating Force (-RT1 option):
-RT1 option increases
unmating force up to 50% **RoHS Compliant:**

Processing:

Max Processing Temp: 230°C for 60 seconds, or 260°C for 20 seconds 3x Lead-Free Solderable:

SMT Lead Coplanarity: (0,10mm) .004" max (030-060) (0,15mm) .006" max (090-120) Board Stacking:

For applications requiring more than two connectors per board or 120 positions or higher, contact ipg@samtec.com

APPLICATION

SPECIFIC OPTION

placement/inspection machines may

have component height restrictions.

Please consult machinery specifications.) • 30µ" (0,76µm) Gold (Specify -H plating

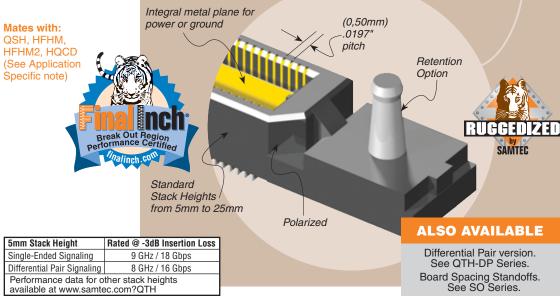
for Data Rate cable mating applications.)

• 14mm, 15mm, 22mm and 30mm stack height (Caution: Some automatic

• Edge Mount & Guide Posts

• 150 positions per row

Call Samtec.



NO. OF POSITIONS **PER ROW**

PLATING **LEAD OPTION** STYLE



= (7,00mm) .275" DIA Polyimide film

Pick & Place Pad

-TR

= Tape & Reel

(–090 positions

maximum)

-RT1

Retention Option

(-01 Lead Style

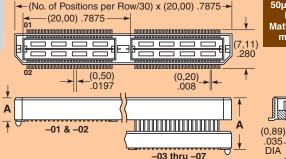
only & -090 positions

maximum)

030, –060, –090, –120 (60 total positions per bank)

LEAD **STYLE** from chart.

LEAD STYLE	A	HEIGHT WITH QSH
-01	(4,27) .168	(5,00) .198
-02	(7,26) .286	(8,00) .316
-03	(10,27) .404	(11,00) .433
-04	(15,25) .600	(16,00) .630
-05	(18,24) .718	(19,00) .748
-07	(24,24) .954	(25,00) .984
D/00) (00 00) 707F .		



= 10µ" (0,25µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

_C*

= Electro-Polished Selective 50μ" (1,27μm) min Au over 150μ" (3,81μm) Ni on Signal Pins in contact area, 10μ" (0,25μm) min Au over 50μ" (1,27μm) Ni on Ground Plane in contact area, Matte Tin over 50μ" (1,27μm) min Ni on all solder tails

-01

(3,30)062

Note: Some lengths, styles

and options are non-standard, non-returnable.

*Note: -C Plating passes

10 year MFG testing

Due to technical progress, all designs, specifications and components are subject to change without notice.

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